

Part Number: Applicable to ASF, ASL, ASW, ASX, AWB, AWG, ABB, ABU series

Product Name: GaAs Amplifier

Package Type: SOT89

Package Elements	Constituents	CAS No.	Weight (mg)	Weight %
Active Semiconductor Die	GaAs	1303-00-0	0.257	85
	Au	7440-57-5	0.045	15
Leadframe	Cu	7440-50-8	23.328	99.80
	Fe	7439-89-6	0.023	0.10
	Р	7723-14-0	0.009	0.04
	Ag	7440-22-4	0.014	0.06
Leadframe Plating	Sn	7440-31-5	1.400	100
Epoxy Molding Compound	Epoxy Resin A	Trade secret	1.3946	5.00
	Epoxy Resin B	29690-82-2	1.3946	5.00
	Phenolic Resin	Trade secret	1.3946	5.00
	Silica (Amorphous) A	60676-86-0	22.173	79.50
	Silica (Amorphous) B	7631-86-9	1.3946	5.00
	Carbon Black	1333-86-4	0.139	0.50
Epoxy Resin	Silver Powder	7440-22-4	0.113	84.00
	Epoxy Resin	9003-36-5	0.007	5.00
	Diluent A	Trade Secret	0.003	2.50
	Diluent B	3101-60-8	0.003	2.50
	Hardener A	Trade Secret	0.003	2.50
	Hardener B	Trade Secret	0.003	2.50
	Solvent	Trade Secret	0.001	0.50
	Organic Peroxide	Trade Secret	0.001	0.50
Wire	Au	7440-57-5	0.038	100
Total			53.138	

This information sheet is to declare all substances intentionally added in our SOT89 semiconductor products. Total weight of the package varies depending on active die size. The material data is evidenced by written declaration from our packaging company. The products listed above DO NOT CONTAIN intentionally added hazardous materials such as cadmium (Cd), mercury (Hg), hexavalent chromium (Cr⁶⁺), polybrominated biphenyls (PBBs), polybrominated diphenylethers (PBDEs), bis(2-ethylhexyl) phthalate (DEHP), butyl benzyl phthalate (BBP), dibutyl phthalate (DBP), and diisobutyl phthalate (DIBP) except for 0.01 wt.% of lead (Pb), which COMPLY with the *RoHS3 Directive* 2015/863/EU. For further information, contact our Sales Department at sales@asb.co.kr.

Authorized Signature, ASB Inc

This data is based on information provided by our suppliers and we do not validate it by measurement. ASB Inc. assumes no responsibility in connection with any use of this information. The information is subject to change without notice.

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